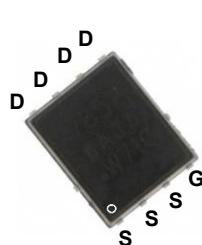
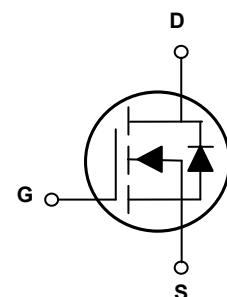


## Main Product Characteristics

BV <sub>DSS</sub>	80V
R <sub>DS(ON)</sub>	3.9mΩ
I <sub>D</sub>	100A



PPAK 5x6



Schematic Diagram

## Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



## Description

The SSFP8974 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

## Absolute Maximum Ratings (T<sub>C</sub>=25°C unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	V <sub>DS</sub>	80	V
Gate-Source Voltage	V <sub>GS</sub>	+20/-12	V
Drain Current-Continuous (T <sub>C</sub> =25°C)	I <sub>D</sub>	100	A
Drain Current-Continuous (T <sub>C</sub> =100°C)		63	
Drain Current-Pulsed <sup>1</sup>	I <sub>DM</sub>	400	A
Single Pulse Avalanche Energy <sup>2</sup>	E <sub>AS</sub>	245	mJ
Single Pulse Avalanche Current <sup>2</sup>	I <sub>AS</sub>	70	A
Power Dissipation (T <sub>C</sub> =25°C)	P <sub>D</sub>	142	W
Power Dissipation-Derate above 25°C		1.14	W/°C
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub>	62	°C/W
Thermal Resistance, Junction-to-Case	R <sub>θJC</sub>	0.88	°C/W
Operating Junction Temperature Range	T <sub>J</sub>	-50 To +150	°C
Storage Temperature Range	T <sub>STG</sub>	-50 To +150	°C

**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On/Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	80	-	-	V
$\text{BV}_{\text{DSS}}$ Temperature Coefficient	$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	Reference to $25^\circ\text{C}$ , $I_{\text{D}}=1\text{mA}$	-	0.03	-	$\text{V}/^\circ\text{C}$
Drain-Source Leakage Current	$I_{\text{DSS}}$	$V_{\text{DS}}=80\text{V}, V_{\text{GS}}=0\text{V}, T_J=25^\circ\text{C}$	-	-	1	$\mu\text{A}$
		$V_{\text{DS}}=64\text{V}, V_{\text{GS}}=0\text{V}, T_J=85^\circ\text{C}$	-	-	10	$\mu\text{A}$
Gate-Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	100	nA
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=20\text{A}$	-	3.2	3.9	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=10\text{A}$	-	4.6	6.2	
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=250\mu\text{A}$	1.2	1.6	2.5	V
$V_{\text{GS}(\text{th})}$ Temperature Coefficient	$\Delta V_{\text{GS}(\text{th})}$		-	-5.8	-	$\text{mV}/^\circ\text{C}$
Forward Transconductance	$g_{\text{fs}}$	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=5\text{A}$	-	10	-	S
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge <sup>3,4</sup>	$Q_g$	$V_{\text{DS}}=64\text{V}, I_{\text{D}}=10\text{A}, V_{\text{GS}}=10\text{V}$	-	88	132	nC
Gate-Source Charge <sup>3,4</sup>	$Q_{\text{gs}}$		-	10.2	15	
Gate-Drain Charge <sup>3,4</sup>	$Q_{\text{gd}}$		-	24	32	
Turn-On Delay Time <sup>3,4</sup>	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=40\text{V}, R_{\text{G}}=6\Omega, V_{\text{GS}}=10\text{V}, I_{\text{D}}=1\text{A}$	-	20	40	nS
Rise Time <sup>3,4</sup>	$t_r$		-	13	26	
Turn-Off Delay Time <sup>3,4</sup>	$t_{\text{d}(\text{off})}$		-	36	72	
Fall Time <sup>3,4</sup>	$t_f$		-	18	36	
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}, F=1\text{MHz}$	-	5160	10200	pF
Output Capacitance	$C_{\text{oss}}$		-	1346	2700	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	40	80	
Gate Resistance	$R_g$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=0\text{V}, F=1\text{MHz}$	-	1.65	-	$\Omega$
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Continuous Source Current	$I_s$	$V_G=V_D=0\text{V}, \text{Force Current}$	-	-	100	A
Pulsed Source Current	$I_{\text{SM}}$		-	-	200	A
Diode Forward Voltage	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_s=1\text{A}, T_J=25^\circ\text{C}$	-	-	1	V

Note:

1. Repetitive rating: Pulsed width limited by maximum junction temperature.
2.  $V_{\text{DD}}=25\text{V}, V_{\text{GS}}=10\text{V}, L=0.1\text{mH}, I_{\text{AS}}=70\text{A}, R_{\text{G}}=25\Omega$ , starting  $T_J=25^\circ\text{C}$ .
3. Pulse test: pulse width  $\leq 300\text{us}$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operation temperature.

## Typical Electrical and Thermal Characteristic Curves

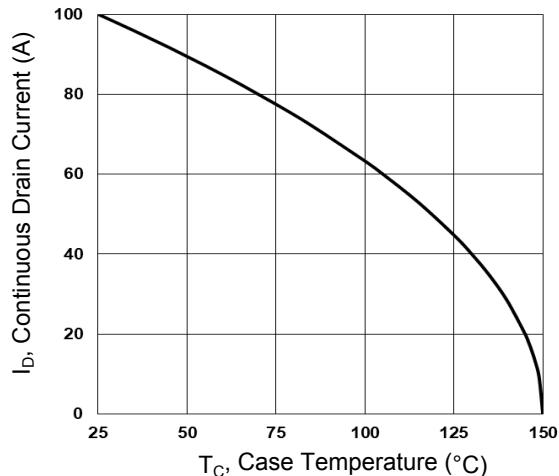


Figure 1. Continuous Drain Current vs. T<sub>c</sub>

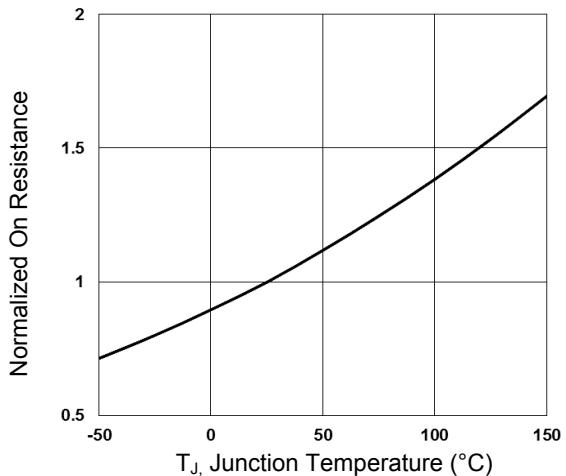


Figure 2. Normalized R<sub>DS(ON)</sub> vs. T<sub>j</sub>

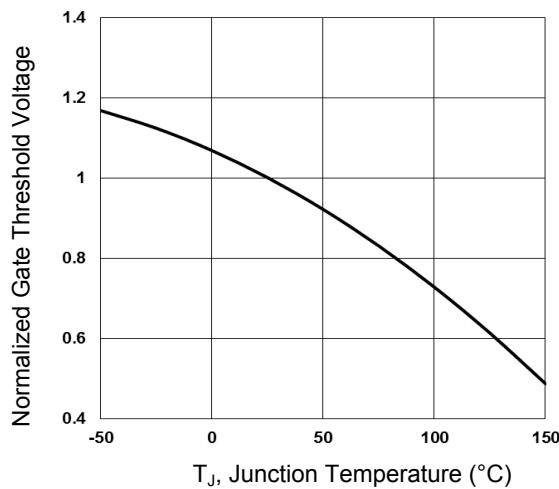


Figure 3. Normalized V<sub>th</sub> vs. T<sub>j</sub>

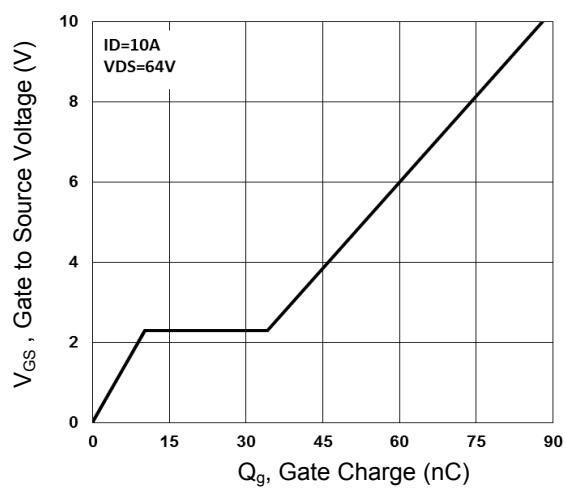


Figure 4. Gate Charge Characteristics

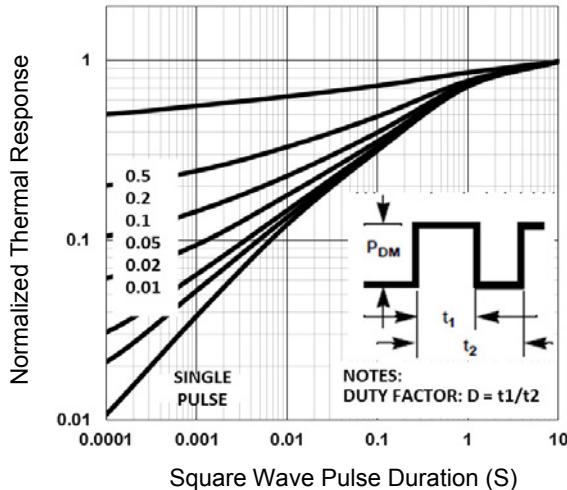


Figure 5. Normalized Transient Impedance

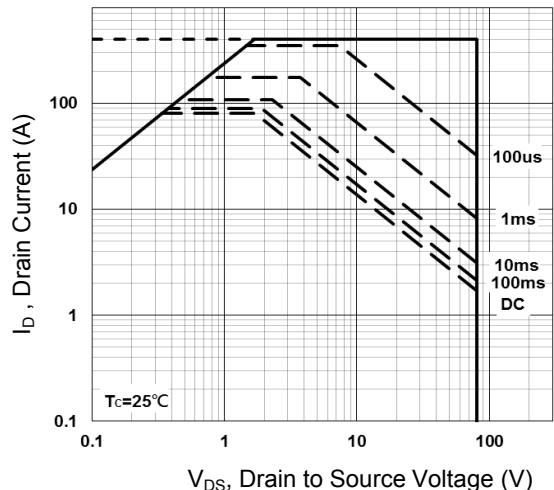


Figure 6. Maximum Safe Operation Area

## Typical Electrical and Thermal Characteristic Curves

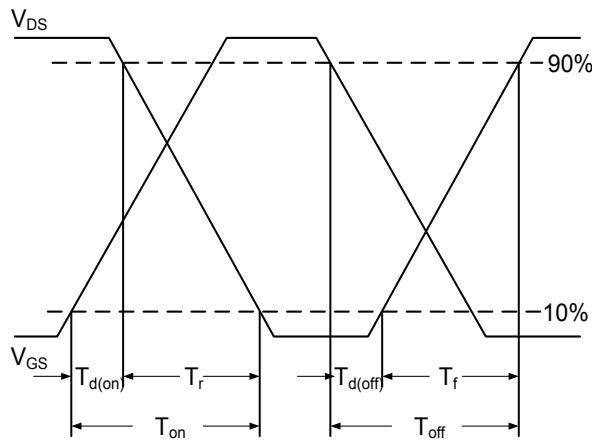


Figure 7. Switching Time Waveform

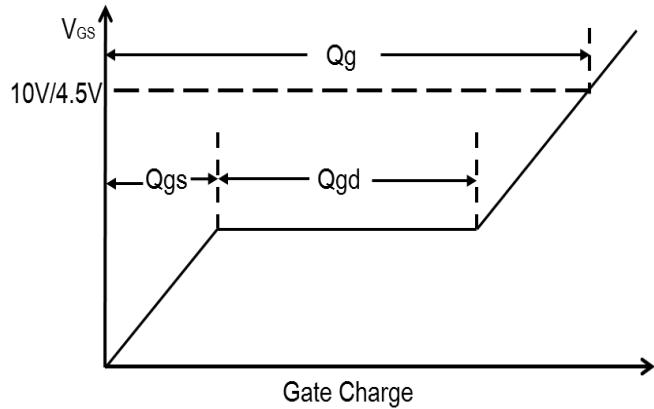
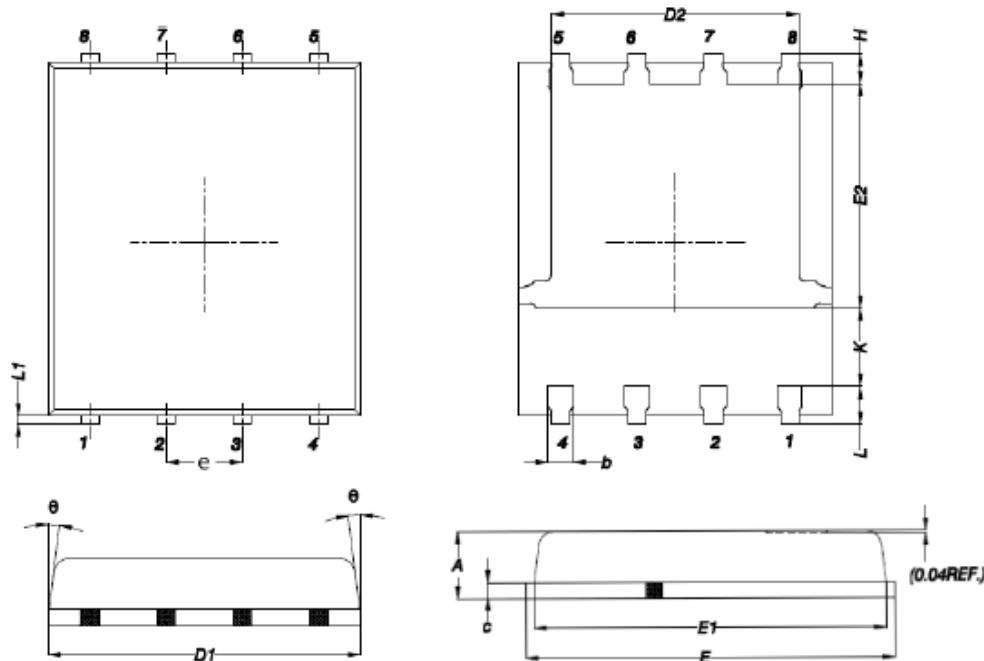


Figure 8. Gate Charge Waveform

### Package Outline Dimensions PPAK5x6



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.200	0.850	0.047	0.031
b	0.510	0.300	0.020	0.012
C	0.300	0.200	0.012	0.008
D1	5.400	4.800	0.212	0.189
D2	4.310	3.610	0.170	0.142
E	6.300	5.850	0.248	0.230
E1	5.960	5.450	0.235	0.215
E2	3.920	3.300	0.154	0.130
e	1.27BSC		0.05BSC	
H	0.650	0.380	0.026	0.015
K	-	1.100	-	0.043
L	0.710	0.380	0.028	0.015
L1	0.250	0.050	0.009	0.002
θ	12°	0°	12°	0°